



SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics - Samsung P/N : CL10C120JB8NNNC

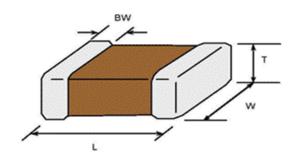
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 12pF, 50V, ± 5%, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>120</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Cerai	mic Capacitor		
② Size	0603 (inch code)	L: 1.60 ± 0.10 mm	W: 0.80 ± 0.10 mm	
③ Dielectric	COG	8 Inner electrode	Ni	
Capacitance	12 pF	Termination	Cu	
⑤ Capacitance	± 5 %	Plating	Sn 100% (Pb Free)	
tolerance		Product	Normal	
6 Rated Voltage	50 V	Special	Reserved for future use	
7 Thickness	0.80 ± 0.10 mm	① Packaging	Cardboard Type, 7" reel	

B. Structure and dimension



Samsung P/N	Dimension(mm)				
(Lead Free)	L	W	Т	BW	
CL10C120JB8NNNC	1.60 ± 0.10	0.80 ± 0.10	0.80 ± 0.10	0.30 ± 0.20	

C. Samsung Reliability Test and Judgement condition

CapacitanceWithin specified tolerance1Mt±10%0.5~5VrmsQ640 minRated Voltage60~120 sec.Insulation10,000Mohm or 500Mohm×μFRated Voltage60~120 sec.ResistanceWhichever is smallerMicroscope (*10)AppearanceNo abnormal exterior appearanceMicroscope (*10)WithstandingNo dielectric breakdown or voltage300% of the rated voltageTemperatureC0GCharacteristics(From -55 ℃ to 125 ℃, Capacitance change should be within ±30PPM/ ℃)Adhesive Strength of TerminationNo peeling shall be occur on the terminal electrode500g×F, for 10±1 sec.Bending StrengthCapacitance change : within ±5% or ±0.5 pF whichever is largerBending to the limit (1mm) within 1.0mm/sec.SolderabilityMore than 75% of terminal surfaceSnAg3.0Cu0.5 solder
Insulation 10,000Mohm or 500Mohm×µF Rated Voltage 60~120 sec. Resistance Whichever is smaller Microscope (*10) Appearance No abnormal exterior appearance Microscope (*10) Withstanding No dielectric breakdown or 300% of the rated voltage Voltage mechanical breakdown Temperature C0G Characteristics (From -55 °C to 125 °C, Capacitance change should be within ±30PPM/°C) Adhesive Strength No peeling shall be occur on the 500g×F, for 10±1 sec. of Termination terminal electrode Bending to the limit (1mm) Bending Strength Capacitance change : with 1.0mm/sec. Solderability More than 75% of terminal surface SnAg3.0Cu0.5 solder
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is to be soldered newly 245±5 °C, 3±0.3sec.
(preheating : 80~120 ℃ for 10~30sec.)
Resistance to Capacitance change : Solder pot : 270±5°C, 10±1sec.
Soldering heat within ±2.5% or ±0.25pF whichever is larger
Tan δ, IR : initial spec.
Vibration Test Capacitance change : Amplitude : 1.5mm
within ±2.5% or ±0.25pF whichever is larger From 10Hz to 55Hz (return : 1min.)
Tan δ, IR: initial spec. 2hours ´3 direction (x, y, z)
Moisture Capacitance change : With rated voltage
Resistance within ±7.5% or ±0.75pF whichever is larger 40±2°C, 90~95%RH, 500+12/-0hrs
Q: 140 min
IR: 500Mohm or 25Mohm × μ F
Whichever is smaller
High Temperature Capacitance change : With 200% of the rated voltage
Resistance within ±3% or ±0.3pF whichever is larger Max. operating temperature
Q: 305 min 1000+48/-0hrs
IR: 1,000Mohm or 50Mohm × μ F
Whichever is smaller
Temperature Capacitance change : 1 cycle condition
Cycling within $\pm 2.5\%$ or $\pm 0.25 pF$ whichever is larger Min. operating temperature \rightarrow 25 °C
Tan δ, IR : initial spec. \rightarrow Max. operating temperature \rightarrow 25 °C
5 cycle test

^{*} The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5℃, 10sec. Max)



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

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We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

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- ① Aerospace/Aviation equipment
- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- Military equipment
- 5 Disaster prevention/crime prevention equipment
- Any other applications with the same as or similar complexity or reliability to the applications set forth above.